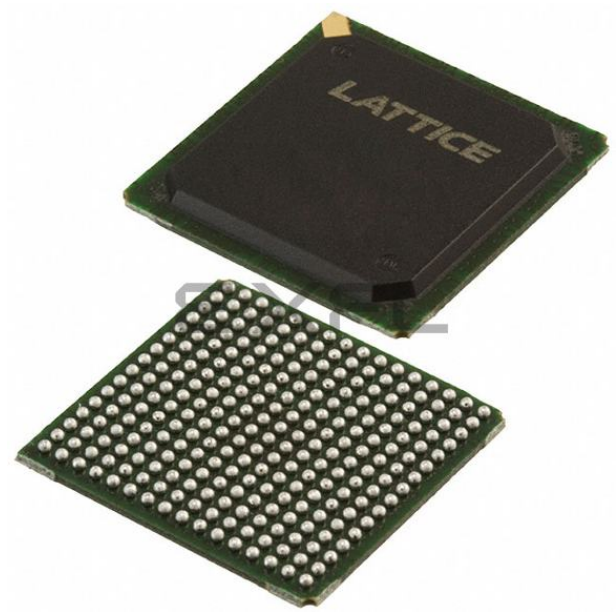
Lattice Semiconductor Corporation - LC5256MV-75FN256I Datasheet



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Understanding Embedded - CPLDs (Complex Programmable Logic Devices)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details	
Product Status	Obsolete
Programmable Type	In System Programmable
Delay Time tpd(1) Max	7.5 ns
Voltage Supply - Internal	3V ~ 3.6V
Number of Logic Elements/Blocks	8
Number of Macrocells	256
Number of Gates	-
Number of I/O	141
Operating Temperature	-40°C ~ 105°C (TJ)
Mounting Type	Surface Mount
Package / Case	256-BGA
Supplier Device Package	256-FPBGA (17x17)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lc5256mv-75fn256i

Cascading For Wide Operation

In several modes it is possible to cascade adjacent MFBs to support wider operation. Table 2 details the different cascading options. There are chains of MFBs in each device which determine those MFBs that are adjacent for the purposes of cascading. Table 3 indicates these chains. The ispXPLD 5000MX design tools automatically cascade blocks if required by a particular design.

Table 2. Cascading Modes For Wide Support

Mode	Cascading Function
Logic	**Input Width.** Allows two MFBs to act as a 136-input block.
	Arithmetic. Allow the carry chain to pass between two MFBs.
FIFO	**Memory Width Expansion.** Allows MFBs to be cascaded for greater width support.
CAM	**Memory Width Expansion.** Allows up to four MFBs to be cascaded for greater width support.

Table 3. MFB Cascade Chain

Device	MFBs in Cascade Chain
ispXPLD 5256MX	A → B → C → D
	H -> G -> F -> E
ispXPLD 5512MX	A → B → C → D → E → F → G → H
	P → O → N → M → L → K → J → I
ispXPLD 5768MX	D → C → B → A → X → W → V → U → T → S → R → Q
	E → F → G → H → I → J → K → L → M → N → O → P
ispXPLD 51024MX	H → G → F → E → D → C → B → A → AF → AE → AD → AC → AB → AA → Z → Y
	I → J → K → L → M → N → O → P → Q → R → S → T → U → V → W → X

SuperWIDE Logic Mode

In logic mode, each MFB contains 32 macrocells and a fully populated, programmable AND-array with 160 logic product terms and four control product terms. The MFB has 68 inputs from the Global Routing Pool, which are available in both true and complement form for every product term. It is also possible to cascade adjacent MFBs to create a block with 136 inputs. The four control product terms are used for shared reset, clock, clock enable, and output enable functions. Figure 3 shows the overall structure of the MFB in logic mode while Figure 4 provides a more detailed view from the perspective of a macrocell slice.

Figure 3. MFB in SuperWIDE Logic Mode†

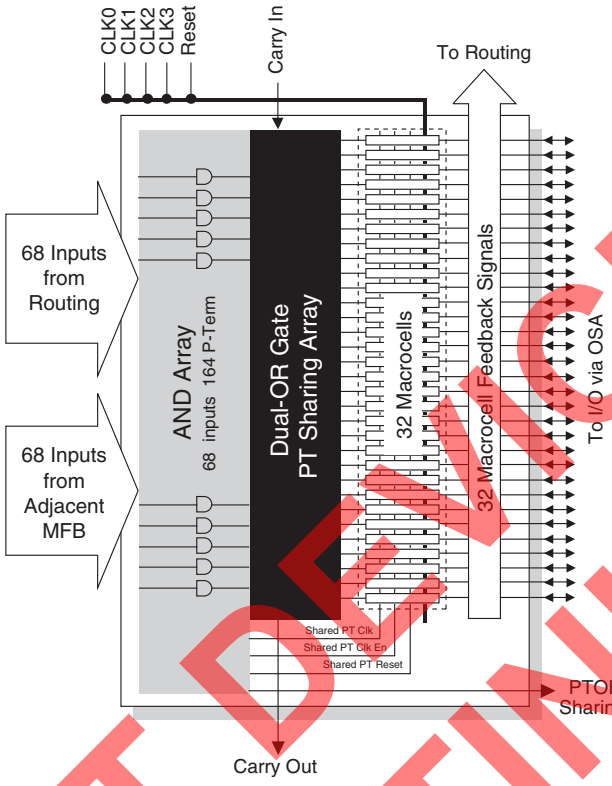
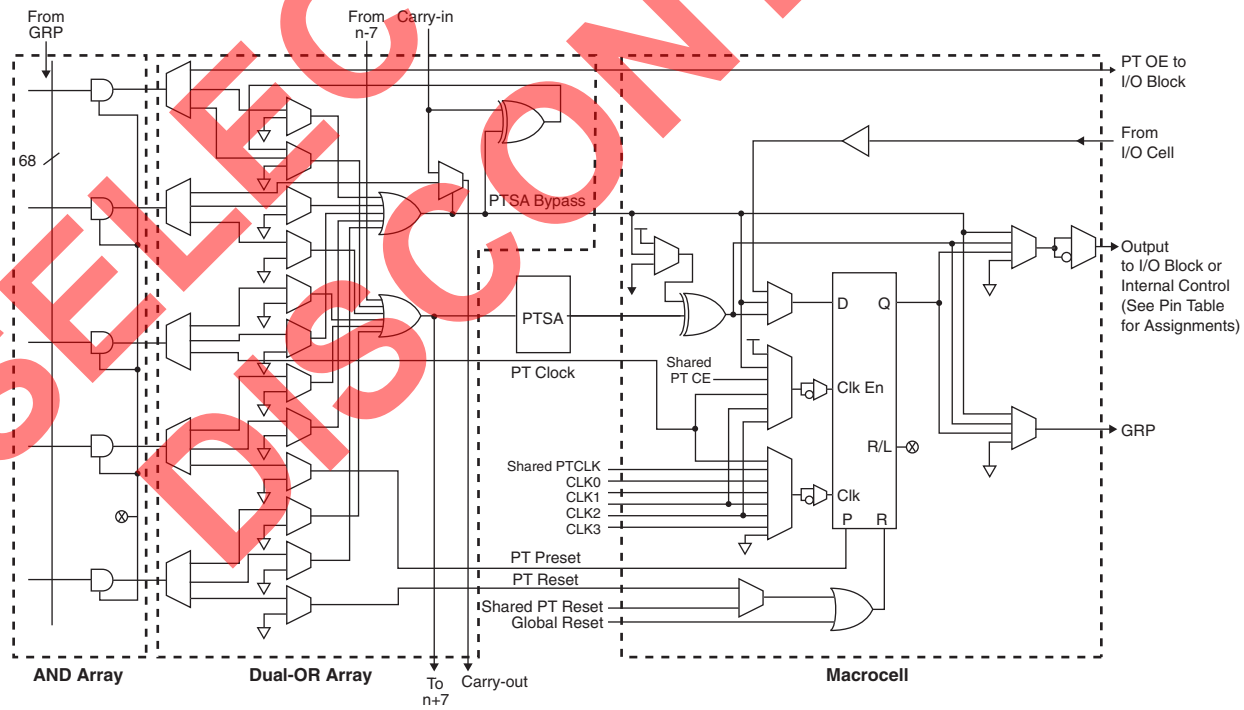


Figure 4. Macrocell Slice in Logic Mode AND-Array



True Dual-Port SRAM Mode

In Dual-Port SRAM Mode the multi-function array is configured as a dual port SRAM. In this mode two independent read/write ports access the same 8,192-bits of memory. Data widths of 1, 2, 4, 8, and 16 are supported by the MFB. Figure 9 shows the block diagram of the dual port SRAM.

Write data, address, chip select and read/write signals are always synchronous (registered.) The output data signals can be synchronous or asynchronous. Resets are asynchronous. All inputs on the same port share the same clock, clock enable, and reset selections. All outputs on the same port share the same clock, clock enable, and reset selections. Selections may be made independently between both inputs and outputs and ports. Table 5 shows the possible sources for the clock, clock enable and initialization signals for the various registers.

Figure 9. Dual-Port SRAM Block Diagram

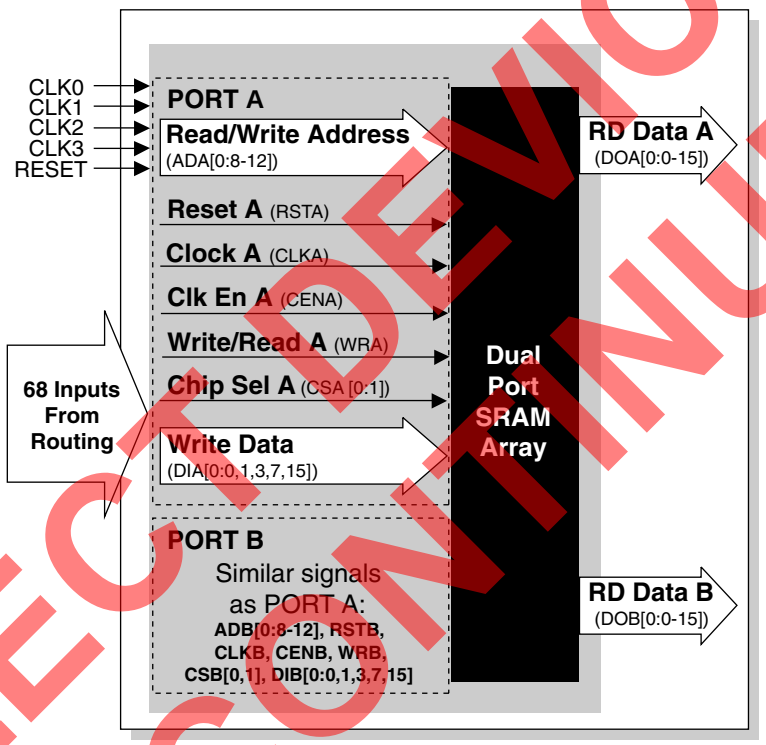


Table 5. Register Clock, Clock Enable, and Reset in Dual-Port SRAM Mode

Register	Input	Source
Address, Write Data, Read Data, Read/ Write, and Chip Select	Clock	CLKA (CLKB) or one of the global clocks (CLK0 - CLK3). The selected signal can be inverted if desired.
	Clock Enable	CENA (CENB) or one of the global clocks (CLK1 - CLK 2). The selected signal can be inverted if required.
	Reset	Created by the logical OR of the global reset signal and RSTA (RSTB). RSTA (RSTB) can be inverted is desired.

Pseudo Dual-Port SRAM Mode

In Pseudo Dual-Port SRAM Mode the multi-function array is configured as a SRAM with an independent read and write ports that access the same 16,384-bits of memory. Data widths of 1, 2, 4, 8, 16 and 32 are supported by the MFB. Figure 10 shows the block diagram of the Pseudo Dual-Port SRAM.

Write data, write address, chip select and write enable signals are always synchronous (registered). The read data and read address signals can be synchronous or asynchronous. Reset is asynchronous. All write signals share the same clock, and clock enable. All read signals share the same clock and clock enable. Reset is shared by both read and write signals. Table 6 shows the possible sources for the clock, clock enable and initialization signals for the various registers.

Figure 10. Pseudo Dual-Port SRAM Block Diagram

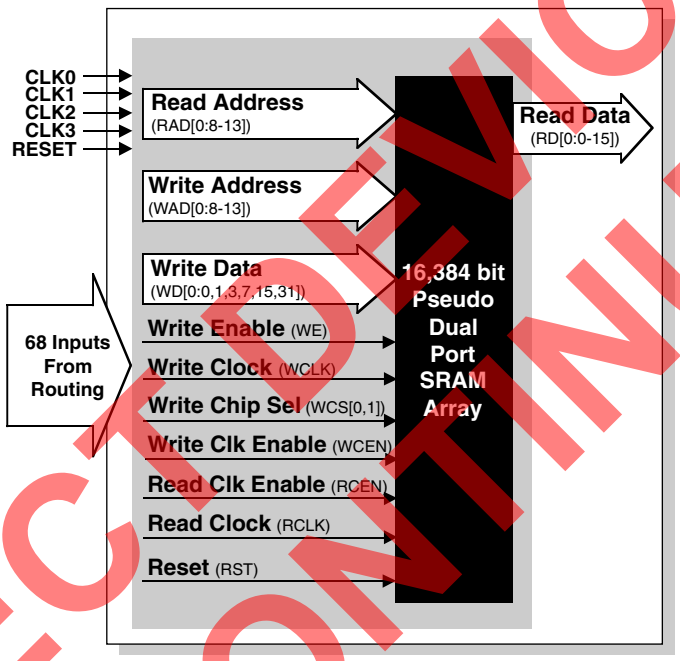


Table 6. Register Clock, Clock Enable, and Reset in Pseudo Dual-Port SRAM Mode

Register	Input	Source
Write Address, Write Data, Write Enable, and Write Chip Select	Clock	WCLK or one of the global clocks (CLK0 - CLK3). The selected signal can be inverted if desired.
	Clock Enable	WCEN or one of the global clocks (CLK1 - CLK2). The selected signal can be inverted if desired.
	Reset	Created by the logical OR of the global reset signal and RST. RST may have inversion if desired.
Read Data and Read Address	Clock	RCLK or one of the global clocks (CLK0 - CLK3). The selected signal can be inverted if desired.
	Clock Enable	RCEN or one of the global clocks (CLK1 - CLK2). The selected signal can be inverted if desired.
	Reset	Created by the logical OR of the global reset signal and RST. RST may have inversion if desired.

Figure 15. PLL Block Diagram

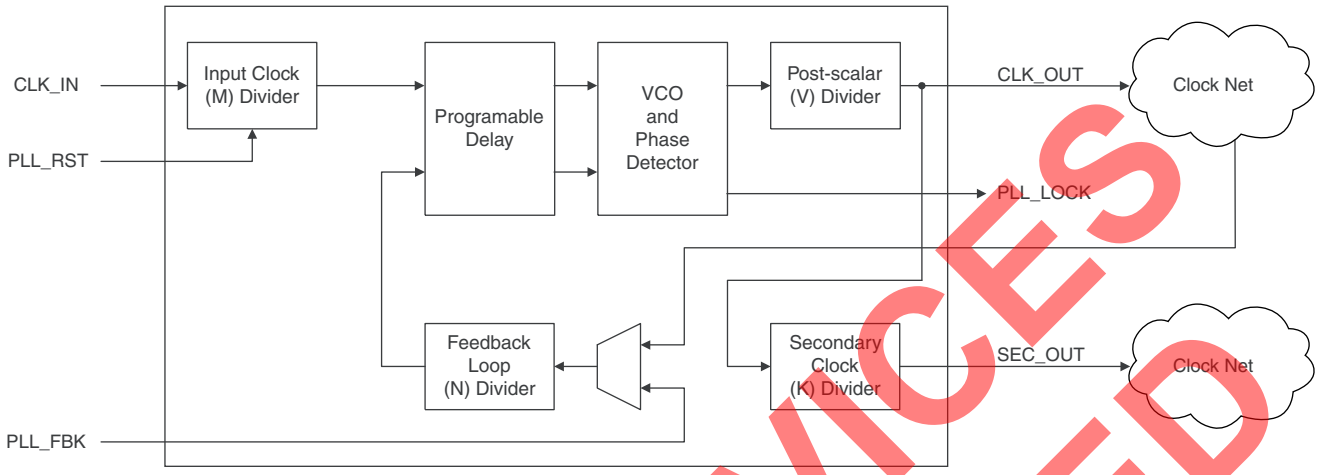
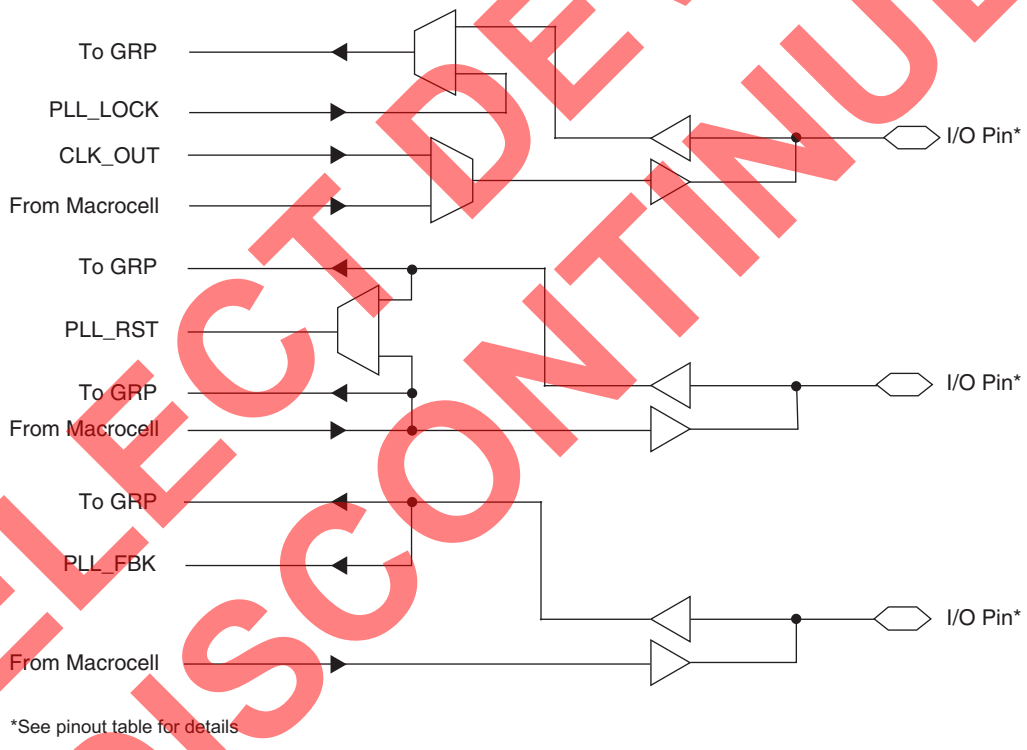


Figure 16. Connection of Optional PLL Inputs and Outputs



In order to facilitate the multiply and divide capabilities of the PLL, each PLL has dividers associated with it: M, N and K. The M divider is used to divide the clock signal, while the N divider is used to multiply the clock signal. The K divider is only used when a secondary clock output is needed. This divider divides the primary clock output and feeds to a separate global clock net. The V divider is used to provide lower frequency output clocks, while maintaining a stable, high frequency output from the PLL's VCO circuit. The PLL also has a delay feature that allows the output clock to be advanced or delayed to improve set-up and clock-to-out times for better performance. For more information on the PLL, please refer to TN1003, sysCLOCK PLL Usage Guide for ispXPGA, ispGDX2, ispXPLD and ispMACH 5000VG Devices.

Figure 17. I/O Cell

Table 10. Shared PTOE Segments

Device	MFBs Associated With Segments
ispXPLD 5256MX	(A, B, C, D) (E, F, G, H)
ispXPLD 5512MX	(A, B, C, D) (E, F, G, H) (I, J, K, L) (M, N, O, P)
ispXPLD 5768MX	(A, B, C, D) (E, F, G, H) (I, J, K, L) (M, N, O, P) (Q, R, S, T) (U, V, W, Z)
ispXPLD 51024MX	(A, B, C, D) (E, F, G, H) (I, J, K, L) (M, N, O, P) (Q, R, S, T) (U, V, W, Z) (Y, Z, AA, AB) (AC, AD, AE, AF)

sysIO Standards

Each I/O within a bank is individually configurable based on the V_{CCO} and V_{REF} settings. Some standards also require the use of an external termination voltage. Table 12 lists the sysIO standards with the typical values for V_{CCO}, V_{REF} and V_{TT}. For more information on the sysIO capability, refer to TN1000, sysIO Usage Guidelines for Lattice Devices.

Table 11. Number of I/Os per Bank

Device	Maximum Number of I/Os per Bank (n)
ispXPLD 5256MX	36
ispXPLD 5512MX	68
ispXPLD 5768MX	96
ispXPLD 51024MX	96

sysCONFIG Interface

In addition to being able to program the device through the IEEE 1532 interface a microprocessor style interface (sysCONFIG interface) allows reconfiguration of the SRAM bits within the device. For more information on the sysCONFIG capability, refer to TN1026, ispXP Configuration Usage Guidelines.

Security Scheme

A programmable security scheme is provided on the ispXPLD 5000MX devices as a deterrent to unauthorized copying of the array configuration patterns. Once programmed, this bit prevents readback of the programmed pattern by a device programmer, securing proprietary designs from competitors. The security bit also prevents programming and verification. The entire device must be erased in order to erase the security bit.

Low Power Consumption

The ispXPLD 5000MX devices use zero power non-volatile cells along with full CMOS design to provide low static power consumption. The 1.8V core reduces dynamic power consumption compared with devices with higher core voltages. For information on estimating power consumption, refer to TN1031 Power Estimation in ispXPLD 5000MX Devices.

Density Migration

The ispXPLD 5000MX family has been designed to ensure that different density devices in the same package have compatible pin-outs. Furthermore, the architecture ensures a high success rate when performing design migration from lower density parts to higher density parts. In many cases, it is possible to shift a lower utilization design targeted for a high-density device to a lower density device. However, the exact details of the final resource utilization will impact the likely success in each case.

IEEE 1149.1-Compliant Boundary Scan Testability

All ispXPLD 5000MX devices have boundary scan cells and are compliant to the IEEE 1149.1 standard. This allows functional testing of the circuit board on which the device is mounted through a serial scan path that can access all critical logic notes. Internal boundary scan registers are linked internally, allowing test data to be shifted in and loaded directly onto test nodes, or test node data to be captured and shifted out for verification. In addition, these devices can be linked into a board-level serial scan path for board-level testing. The test access port has its own supply voltage and can operate with LVCMOS3.3, 2.5 and 1.8V standards.

sysIO Quick Configuration

To facilitate the most efficient board test, the physical nature of the I/O cells must be set before running any continuity tests. As these tests are fast, by nature, the overhead and time that is required for configuration of the I/Os' physical nature should be minimal so that board test time is minimized. The ispXPLD 5000MX family of devices allows this by offering the user the ability to quickly configure the physical nature of the sysIO cells. This quick configuration takes milliseconds to complete, whereas it takes seconds for the entire device to be programmed. Lattice's ispVM™ System programming software can either perform the quick configuration through the PC parallel port, or can generate the ATE or test vectors necessary for a third-party test system.

Supply Current

Symbol	Parameter	Condition	Min.	Typ.[3]	Max.	Units
ispXPLD 5256						
I_{CC}[1,2]	Operating Power Supply Current	V_{CC} = 3.3V, f = 1.0MHz	—	26	—	mA
		V_{CC} = 2.5V, f = 1.0MHz	—	26	—	mA
		V_{CC} = 1.8V, f = 1.0MHz	—	16	—	mA
I_{CCO}	Standby Power Supply Current (per I/O Bank)	V_{CCO} = 3.3V, f = 1.0MHz, unloaded	—	4	—	mA
		V_{CCO} = 2.5V, f = 1.0MHz, unloaded	—	4	—	mA
		V_{CCO} = 1.8V, f = 1.0MHz, unloaded	—	3	—	mA
I_{CCP}	PLL Power Supply Current (per PLL Bank)	V_{CCP} = 3.3V, f = 10MHz	—	11	—	mA
		V_{CCP} = 2.5V, f = 10MHz	—	11	—	mA
		V_{CCP} = 1.8V, f = 10MHz	—	3	—	mA
I_{CCJ}	Standby IEEE 1149.1 TAP Power Supply Current	V_{CCJ} = 3.3V	—	1	—	mA
		V_{CCJ} = 2.5V	—	1	—	mA
		V_{CCJ} = 1.8V	—	1	—	mA
ispXPLD 5512						
I_{CC}[1,2]	Operating Power Supply Current	V_{CC} = 3.3V, f = 1.0MHz	—	33	—	mA
		V_{CC} = 2.5V, f = 1.0MHz	—	33	—	mA
		V_{CC} = 1.8V, f = 1.0MHz	—	22	—	mA
I_{CCO}	Standby Power Supply Current (per I/O Bank)	V_{CCO} = 3.3V, f = 1.0MHz, unloaded	—	4	—	mA
		V_{CCO} = 2.5V, f = 1.0MHz, unloaded	—	4	—	mA
		V_{CCO} = 1.8V, f = 1.0MHz, unloaded	—	3	—	mA
I_{CCP}	PLL Power Supply Current (per PLL Bank)	V_{CCP} = 3.3V, f = 10MHz	—	11	—	mA
		V_{CCP} = 2.5V, f = 10MHz	—	11	—	mA
		V_{CCP} = 1.8V, f = 10MHz	—	3	—	mA
I_{CCJ}	Standby IEEE 1149.1 TAP Power Supply Current	V_{CCJ} = 3.3V	—	1	—	mA
		V_{CCJ} = 2.5V	—	1	—	mA
		V_{CCJ} = 1.8V	—	1	—	mA
ispXPLD 5768						
I_{CC}[1,2]	Operating Power Supply Current	V_{CC} = 3.3V, f = 1.0MHz	—	40	—	mA
		V_{CC} = 2.5V, f = 1.0MHz	—	40	—	mA
		V_{CC} = 1.8V, f = 1.0MHz	—	30	—	mA
I_{CCO}	Standby Power Supply Current (per I/O Bank)	V_{CCO} = 3.3V, f = 1.0MHz, unloaded	—	4	—	mA
		V_{CCO} = 2.5V, f = 1.0MHz, unloaded	—	4	—	mA
		V_{CCO} = 1.8V, f = 1.0MHz, unloaded	—	3	—	mA
I_{CCP}	PLL Power Supply Current (per PLL Bank)	V_{CCP} = 3.3V, f = 10MHz	—	11	—	mA
		V_{CCP} = 2.5V, f = 10MHz	—	11	—	mA
		V_{CCP} = 1.8V, f = 10MHz	—	3	—	mA
I_{CCJ}	Standby IEEE 1149.1 TAP Power Supply Current	V_{CCJ} = 3.3V	—	1	—	mA
		V_{CCJ} = 2.5V	—	1	—	mA
		V_{CCJ} = 1.8V	—	1	—	mA

Supply Current (Continued)

Symbol	Parameter	Condition	Min.	Typ.[3]	Max.	Units
ispXPLD 51024						
I_{CC}[1,2]	Operating Power Supply Current	V_{CC} = 3.3V, f = 1.0MHz	—	75	—	mA
		V_{CC} = 2.5V, f = 1.0MHz	—	75	—	mA
		V_{CC} = 1.8V, f = 1.0MHz	—	55	—	mA
I_{CCO}	Standby Power Supply Current (per I/O Bank)	V_{CCO} = 3.3V, f = 1.0MHz, unloaded	—	4	—	mA
		V_{CCO} = 2.5V, f = 1.0MHz, unloaded	—	4	—	mA
		V_{CCO} = 1.8V, f = 1.0MHz, unloaded	—	3	—	mA
I_{CCP}	PLL Power Supply Current (per PLL Bank)	V_{CCP} = 3.3V, f = 10MHz	—	11	—	mA
		V_{CCP} = 2.5V, f = 10MHz	—	11	—	mA
		V_{CCP} = 1.8V, f = 10MHz	—	3	—	mA
I_{CCJ}	Standby IEEE 1149.1 TAP Power Supply Current	V_{CCJ} = 3.3V	—	1	—	mA
		V_{CCJ} = 2.5V	—	1	—	mA
		V_{CCJ} = 1.8V	—	1	—	mA

1. Device configured with 16-bit counters.
2. ICC varies with specific device configuration and operating frequency.
3. T_A = 25°C

ispXPLD 5000MX Family Timing Adders

Parameter	Description	Base Param.	-4		-45		-5		-52		-75		Units
			Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
t_{IOI} Input Adjusters													
LVTTL_in	Using 3.3V TTL	t_{IOIN}	—	0.0	—	0.0	—	0.0	—	0.0	—	0.0	ns
LVCMOS_18_in	Using 1.8V CMOS	t_{IOIN}	—	0.0	—	0.0	—	0.0	—	0.0	—	0.0	ns
LVCMOS_25_in	Using 2.5V CMOS	t_{IOIN}	—	0.0	—	0.0	—	0.0	—	0.0	—	0.0	ns
LVCMOS_33_in	Using 3.3V CMOS	t_{IOIN}	—	0.0	—	0.0	—	0.0	—	0.0	—	0.0	ns
AGP_1X_in	Using AGP 1x	t_{IOIN}	—	1.0	—	1.0	—	1.0	—	1.0	—	1.0	ns
CTT25_in	Using CTT 2.5V	t_{IOIN}	—	1.0	—	1.0	—	1.0	—	1.0	—	1.0	ns
CTT33_in	Using CTT 3.3V	t_{IOIN}	—	1.0	—	1.0	—	1.0	—	1.0	—	1.0	ns
GTL+_in	Using GTL+	t_{IOIN}	—	0.5	—	0.5	—	0.5	—	0.5	—	0.5	ns
HSTL_I_in	Using HSTL 2.5V, Class I	t_{IOIN}	—	0.5	—	0.5	—	0.5	—	0.5	—	0.5	ns
HSTL_III_in	Using HSTL 2.5V, Class III	t_{IOIN}	—	0.6	—	0.6	—	0.6	—	0.6	—	0.6	ns
HSTL_IV_in	Using HSTL 2.5V, Class IV	t_{IOIN}	—	0.6	—	0.6	—	0.6	—	0.6	—	0.6	ns
LVDS_in	Using Low Voltage Differential Signaling (LVDS)	t_{IOIN}	—	0.5	—	0.5	—	0.5	—	0.5	—	0.5	ns
LVPECL_in	Using Low Voltage PECL	t_{IOIN}	—	0.5	—	0.5	—	0.5	—	0.5	—	0.5	ns
PCI_in	Using PCI	t_{IOIN}	—	1.0	—	1.0	—	1.0	—	1.0	—	1.0	ns
SSTL2_I_in	Using SSTL 2.5V, Class I	t_{IOIN}	—	0.5	—	0.5	—	0.5	—	0.5	—	0.5	ns
SSTL2_II_in	Using SSTL 2.5V, Class II	t_{IOIN}	—	0.5	—	0.5	—	0.5	—	0.5	—	0.5	ns
SSTL3_I_in	Using SSTL 3.3V, Class I	t_{IOIN}	—	0.6	—	0.6	—	0.6	—	0.6	—	0.6	ns
SSTL3_II_in	Using SSTL 3.3V, Class II	t_{IOIN}	—	0.6	—	0.6	—	0.6	—	0.6	—	0.6	ns
t_{IOO} Output Adjusters – Output Signal Modifiers													
Slow Slew	Using Slow Slew (LVTTL and LVCMOS Outputs Only)	t_{IOBUF}, t_{IOEN}	—	0.9	—	0.9	—	0.9	—	0.9	—	0.9	ns
t_{IOO} Output Adjusters – Output Configurations													
LVTTL_out	Using 3.3V TTL Drive	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	1.2	—	1.2	—	1.2	—	1.2	—	1.2	ns
LVCMOS_18_4mA_out	Using 1.8V CMOS Standard, 4mA Drive	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	0.3	—	0.3	—	0.3	—	0.3	—	0.3	ns
LVCMOS_18_5.33mA_out	Using 1.8V CMOS Standard, 5.33mA Drive	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	0.3	—	0.3	—	0.3	—	0.3	—	0.3	ns

Signal Descriptions

Signal Names	Descriptions
TMS	Input – This pin is the Test Mode Select input, which is used to control the IEEE 1149.1 state machine.
TCK	Input – This pin is the Test Clock input pin, used to clock the IEEE 1149.1 state machine.
TDI	Input – This pin is the IEEE 1149.1 Test Data in pin, used to load data.
TDO	Output – This pin is the IEEE 1149.1 Test Data out pin used to shift data out.
TOE	Input – Test Output Enable pin. TOE tristates all I/O pins when driven low.
GOE0, GOE1	Input – Global output enable inputs.
RESET	Input – This pin resets all the registers in the device. The global polarity for this pin is selectable on a global basis.þ The default is active low. An external pull-down is required when polarity is set to active high.
yzz	Input/Output – These are the general purpose I/O used by the logic array. *y* is the MFB reference (alpha) and z is the macrocell reference (numeric) y: A-X (768 macrocells) y: A-P (512 macrocells) y: A-H (256 macrocells) z: 0-31
GND	GND – Ground
NC	No connect
V_{CC}	V_{CC} – The power supply pins for core logic.
V_{CCO0}, V_{CCO1}, V_{CCO2}, V_{CCO3}	V_{CC} – The power supply pins for I/O banks 0, 1, 2, and 3.
V_{REF0}, V_{REF1}, V_{REF2}, V_{REF3}	Input – This pin defines the reference voltage for I/O banks 0, 1, 2, and 3.
GCLK0, GCLK1, GCLK2, GCLK3	Input – Global clock/clock enable inputs (see Figure 14 for differential pairing).
CLK_OUT0, CLK_OUT1	Output – Optional clock output from PLL 0 and 1.
PLL_RST0, PLL_RST1	Input – Optional input resets the M divider in PLL 0 and 1.
PLL_FBK0, PLL_FBK1	Input – Optional feedback input for PLL 0 and 1.
GNDP	GND – Ground for PLLs.
V_{CCP}	V_{CC} – The power supply pin for PLLs.
V_{CCJ}	V_{CC} – The power supply for the IEEE 1149.1 interface.
DATA*x*	I/O – sysCONFIG data pins, bit *x*.
CSB	Input – sysCONFIG interface chip select. Drive low to select sysCONFIG interface.
CFG0	Input – Defines SRAM configuration mode. Low: sysCONFIG port, high: E^2CMOS or IEEE 1149.1 TAP.
PROGRAMB	Input – Controls the programming of SRAM. Hold high for normal operation. Toggle low to reload SRAM from E^2 memory.
CCLK[1]	Input – Clock for sysCONFIG interface. Reads and writes occur on the rising edge of the clock.
READ[1]	Input – Drive high to perform reads from the sysCONFIG interface.
INITB	I/O – Indicates status of configuration. Can be driven low to inhibit configuration.
DONE	Output (open drain) – Indicates status of configuration.

1. These inputs should not toggle during power up for proper power-up configuration.

Signals	208 PQFP[4]	256 fpBGA[3, 5]	484 fpBGA, 5[3]	672 fpBGA[3, 5]
VCC	10, 49, 76, 114, 153, 180	D4, D13, F6, F11, L6, L11, N4, N13	A17, A6, AA2, AA21, AB17, AB6, B2, B21, D19, D4, F1, F22, G10, G11, G12, G13, K16, K7, L16, L7, M16, M7, T10, T11, T12, T13, T14, T9, U1, U22, W19, W4	AA21, AA6, F21, F6, G20, G7, J13, J14, K13, K14, L13, L14, M13, M14, N10, N11, N12, N15, N16, N17, N18, N9, P10, P11, P12, P15, P16, P17, P18, P9, R13, R14, T13, T14, U13, U14, V13, V14, Y20, Y7
VCCO0	5, 17, 189, 204	A1, F7, G6	B9, C3, G8, G9, H7, J2, J7, P4	H10, H11, H8, H9, J8, J9, K8, L8, M8, N8
VCCO1	42, 57, 72	K6, L7, T1	AA9, R7, T3, T8, Y3	P8, R8, T8, U8, V8, V9, W10, W11, W8, W9
VCCO2	85, 100, 107, 121	K11, L10, T16	AA14, R16, T15, T20, Y20	P19, R19, T19, U19, V18, V19, W12, W13, W14, W15, W16, W17, W18, W19
VCCO3	146, 161, 176	A16, F10, G11	B14, C20, G14, G15, H16, J16, J21, P19	H12, H13, H14, H15, H16, H17, H18, H19, J18, J19, K19, L19, M19, N19
VCCP	136	J16	M22	N25
VCCJ	27	J1	M1	N4
GND	15, 29, 44, 81, 119, 148, 185, 7, 19, 191, 205, 40, 56, 70, 87, 101, 109, 123, 144, 160, 174	K1, C3, C14, E5, E12, G7, G8, G9, G10, H7, H8, H9, H10, J7, J8, J9, J10, K7, K8, K9, K10, M5, M12, P3	N1, A1, A2, A21, A22, AA1, AA22, AB1, AB22, B1, B22, C15, C8, D11, D12, E18, E5, F17, F6, G16, G7, H10, H11, H12, H13, H14, H15, H20, H3, H8, H9, J10, J11, J12, J13, J14, J15, J8, J9, K10, K11, K12, K13, K14, K15, K8, K9, L10, L11, L12, L13, L14, L15, L19, L4, L8, L9, M10, M11, M12, M13, M14, M19, M4, M9, N10, N11, N12, N13, N14, N9, P10, P11, P12, P13, P14, P9, R10, R11, R12, R13, R14, R15, R8, R9, T16, T7, W11, W12, Y15, Y8	A11, A16, A2, A25, AE1, AE2, AE25, AE26, AF11, AF16, AF2, AF25, B1, B2, B25, B26, J10, J11, J12, J15, J16, J17, K10, K11, K12, K15, K16, K17, K18, K9, L1, L10, L11, L12, L15, L16, L17, L18, L26, L9, M10, M11, M12, M15, M16, M17, M18, M9, N13, N14, P13, P14, R10, R11, R12, R15, R16, R17, R18, R9, T1, T10, T11, T12, T15, T16, T17, T18, T26, T9, U10, U11, U12, U15, U16, U17, U18, U9, V10, V11, V12, V15, V16, V17
GNDP	134	K16	N22	P26
NC[2]	—	**5256MX**: A2, A11, A12, A15, B2, B12, B15, B16, C4, C12, C15, C16, D1, D11, D14, D15, D16, E1, E4, E10, E11, E13, E14, F4, F5, F12, F13, L1, L4, M3, M7, M13, N2, N6, P1, P2, P5, P6, P13, P14, P15, P16, R1, R2, R4, R5, R6, R16, T2, T3, T4, T5, T6 **5512MX/5768MX**: L1	**5512MX**: P1, AA19, AB2, AB21, J17, J6, K1, K17, K18, K19, K2, K20, K21, K22, K3, K4, K5, K6, L1, L17, L18, L2, L20, L21, L22, L3, L5, L6, M15, M17, M18, M2, M20, M21, M3, M5, M6, M8, N15, N17, N18, N19, N2, N20, N21, N3, N4, N5, N6, N8, P15, P17, P18, P2, P21, P22, P5, P6, P8, U17, U6, V18, V5, W6 **5768MX/51024MX**: None	A12, A13, A14, A15, AA10, AA11, AA12, AA13, AA14, AA15, AA16, AA17, AA7, AB10, AB11, AB12, AB13, AB14, AB15, AB16, AB17, AC10, AC11, AC12, AC13, AC14, AC15, AC16, AC17, AD11, AD12, AD13, AD14, AD15, AD16, AE11, AE12, AE13, AE14, AE15, AE16, AF12, AF13, AF14, AF15, B11, B12, B13, B14, B15, B16, C11, C12, C13, C14, C15, C16, C3, D10, D11, D12, D13, D14, D15, D16, D17, E10, E11, E12, E13, E14, E15, E16, E17, E6, E7, E8, F10, F11, F12, F13, F14, F15, F16, F17, G10, G11, G12, G13, G14, G15, G16, G17, Y10, Y11, Y12, Y13, Y14, Y15, Y16, Y17

1. All grounds must be electrically connected at the board level.
2. NC pins should not be connected to any active signals, V_{CC} or GND.
3. Balls for GND, V_{CC} and V_{CCOX} are connected within the substrate to their respective common signals. Pin orientation A1 starts from the upper left corner of the top side view with alphabetical order ascending vertically and numerical order ascending horizontally.
4. Pin orientation follows the conventional counter-clockwise order from pin 1 marking of the topside view.
5. Internal GNDs and I/O GNDs (Bank 0 - Bank 3)þare connected inside package. V_{CCO} balls connect to four power planes within the package, one each for V_{CCOX}.

ispXPLD 5256MX Logic Signal Connections (Continued)

sysIO Bank	LVDS Pair	Primary Macrocell/ Function	Alternate Outputs		Alternate Input	256 fpBGA Ball Number
			Macrocell 1	Macrocell 2		
3	34N	E30	-	-	E31	H14
3	34P	E28	-	-	E29	G16
3	35N	E26	-	-	E27	G15
3	35P	E24/PLL_FBK1	-	-	E25	F15
3	36N	E22/PLL_RST1	E27	F27	E23	H12
3	36P	E21	E26	F26	-	G14
-	-	GND (Bank 3)	-	-	-	GND (Bank 3)
3	37N	E20	E25	F25	-	F16
-	-	VCCO3	-	-	-	VCCO3
3	37P	E18	E24	F24	E19	E16
-	-	GND	-	-	-	GND
3	38N	E16	E23	F23	E17	G13
3	38P	E14	E22	F22	E15	G12
3	39N	E12	E21	F21	E13	F14
3	39P	E10/CLK_OUT1	E20	F20	E11	E15
-	-	VCC	-	-	-	VCC
3	40N	E8	E19	F19	E9	D12
3	40P	E6	E18	F18	E7	B14
3	41N	E5	E17	F17	-	C13
3	41P	E4	E16	F16	-	A14
3	42N	E2	E31	F31	E3	A13
3	42P	E0	E30	F30	E1	B13
-	-	GND (Bank 3)	-	-	-	GND (Bank 3)
-	-	VCCO3	-	-	-	VCCO3
3	43N	F30	E15	F15	F31	B11
3	43P	F28	E14	F14	F29	C11
3	44N	F26	E13	F13	F27	B10
3	44P	F24	E12	F12	F25	A10
3	45N	F22	E11	F11	F23	C10
3	45P	F21	E10	F10	-	D10
3	46N	F20	E9	F9	-	C9
3	46P	F18	E8	F8	F19	E9
3	47N	F16/VREF3	E29	F29	F17	D9
3	47P	F14	E28	F28	F15	F9
3	48N	F12	E7	F7	F13	A9
3	48P	F10	E6	F6	F11	F8
-	-	GND (Bank 3)	-	-	-	GND (Bank 3)
3	49N	F8	E5	F5	F9	E8
-	-	VCCO3	-	-	-	VCCO3
3	49P	F6	E4	F4	F7	A8
3	50N	F5	E3	F3	-	B9
3	50P	F4	E2	F2	-	D8
-	-	VCC	-	-	-	VCC

ispXPLD 5256MX Logic Signal Connections (Continued)

sysIO Bank	LVDS Pair	Primary Macrocell/ Function	Alternate Outputs		Alternate Input	256 fpBGA Ball Number
			Macrocell 1	Macrocell 2		
3	51N	F2	E1	F1	F3	B8
3	51P	F0	E0	F0	F1	C8
0	52N	G30	G31	H31	G31	B7
0	52P	G28	G30	H30	G29	A7
-	-	GND	-	-	-	NC
0	53N	G26	G29	H29	G27	D7
0	53P	G24	G28	H28	G25	C7
0	54N	G22	G27	H27	G23	B6
-	-	VCCO0	-	-	-	VCCO0
0	54P	G21	G26	H26	-	E7
-	-	GND (Bank 0)	-	-	-	GND (Bank 0)
0	55N	G20	G25	H25	-	E6
0	55P	G18	G24	H24	G19	A6
0	56N	G16/VREF0	G3	H3	G17	A5
0	56P	G14	G2	H2	G15	A4
0	57N	G12	G23	H23	G13	B5
0	57P	G10	G22	H22	G11	A3
0	58N	G8	G21	H21	G9	B4
0	58P	G6	G20	H20	G7	B3
0	59N	G5	G19	H19	-	C5
0	59P	G4	G18	H18	-	C6
0	60N	G2	G1	H1	G3	D5
0	60P	G0	G0	H0	G1	D6
-	-	VCCO0	-	-	-	VCCO0
-	-	GND (Bank 0)	-	-	-	GND (Bank 0)

Global Clock LVDS pair options: GCLK0 and GCLK1, as well as GCLK2 and GCLK3, can be paired together to receive differential clocks; where GCLK0 and GCLK3 are the positive LVDS inputs

ispXPLD 5512MX Logic Signal Connections (Continued)

sysIO Bank	LVDS Pair	Primary Macrocell/ Function	Alternate Outputs		Alternate Input	208 PQFP Pin Number	256 fpBGA Ball Number	484 fpBGA Ball Number
			Macrocell 1	Macrocell 2				
—	—	V_{CCO2}	—	—	—	85	V_{CCO2}	V_{CCO2}
2	29N	E10	F5	H5	E11	86	M10	U12
—	—	GND (Bank 2)	—	—	—	87	GND (Bank 2)	GND (Bank 2)
2	30P	E12	F6	H6	E13	88	M11	AB13
2	30N	E16	F7	H7	E17	89	T13	Y13
2	31P	E18	—	—	E19	90	P11	V13
2	31N	E20/V_{REF2}	—	—	E21	91	T14	W13
2	32P	E22	F8	H8	E23	92	R12	V14
2	32N	E24	F9	H9	E25	93	R13	W14
2	33P	E26	F10	H10	E27	94	N11	Y14
2	33N	E28	F11	H11	E29	95	T15	AB14
2	34P	F0	F12	H12	F1	96	R14	AB15
2	34N	F2	F13	H13	F3	97	N12	AA15
2	35P	F4	F14	H14	F5	98	P12	U13
—	—	V_{CCO2}	—	—	—	—	V_{CCO2}	V_{CCO2}
2	35N	F6	F15	H15	F7	99	R15	U14
—	—	GND (Bank 2)	—	—	—	—	GND (Bank 2)	GND (Bank 2)
2	36P	F8	E0	—	F9	—	—	W15
2	36N	F10	E2	—	F11	—	—	W16
2	37P	F12	E4	—	F13	—	—	Y16
2	37N	F16	E6	—	F17	—	—	AA16
2	38P	F18	E8	—	F19	—	—	AB16
2	38N	F20	E10	—	F21	—	—	AA17
2	39P	F22	E12	—	F23	—	—	Y17
2	39N	F24	E16	—	F25	—	—	AA18
2	40P	F26	E20	—	F27	—	—	W17
2	40N	F28	E22	—	F29	—	—	W18
2	41P	G0	—	—	G1	—	—	V15
—	—	V_{CCO2}	—	—	—	100	V_{CCO2}	V_{CCO2}
2	41N	G2	—	—	G3	—	—	U15
—	—	GND (Bank 2)	—	—	—	101	GND (Bank 2)	GND (Bank 2)
2	42P	G4	—	—	G5	102	P13	Y18
2	42N	G6	—	—	G7	103	P15	V17
2	43P	G8	—	—	G9	—	M13	V16
2	43N	G10	—	—	G11	—	P14	U16
2	44P	G12	—	—	G13	—	—	AB18
2	44N	G14	—	—	G15	—	—	AB19
2	45P	G16	—	—	G17	—	—	U18
2	45N	G18	—	—	G19	—	—	T17
2	46P	G20	—	—	G21	104	R16	AB20
2	46N	G22	—	—	G23	105	P16	AA20
2	47P	G24	—	—	G25	106	N15	Y19
—	—	V_{CCO2}	—	—	—	107	V_{CCO2}	V_{CCO2}

ispXPLD 5768MX Logic Signal Connections (Continued)

sysIO Bank	LVDS Pair	Primary Macrocell/ Function	Alternate Outputs		Alternate Inputs	256 fpBGA Ball Number	484 fpBGA Ball Number
			Macrocell 1	Macrocell 2			
3	76P	L30/PLL_FBK1	L0	J0	L31	F15	E21
3	77N	M0/PLL_RST1	P27	N27	M1	H12	G22
3	77P	M2	P26	N26	M3	G14	F21
-	-	GND (Bank 3)	-	-	-	GND (Bank 3)	GND (Bank 3)
3	78N	M4	P25	N25	M5	F16	H21
-	-	VCCO3	-	-	-	VCCO3	VCCO3
3	78P	M6	P24	N24	-	E16	G21
-	-	GND	-	-	-	GND	GND
3	79N	M8	P23	N23	M9	G13	D22
3	79P	M10	P22	N22	M11	G12	D21
3	80N	M12	P21	N21	M13	F14	J20
3	80P	M14/CLK_OUT1	P20	N20	M15	E15	J19
3	81N	M16	N31	-	M17	F12	E20
-	-	VCC	-	-	-	VCC	VCC
3	81P	M18	N30	M30	M19	F13	F20
3	82N	M20	N29	M28	M21	D16	H17
3	82P	M22	N28	M26	M23	D15	H18
-	-	GND (Bank 3)	-	-	-	GND (Bank 3)	GND (Bank 3)
3	83N	M24	N27	-	M25	—	J18
-	-	VCCO3	-	-	-	VCCO3	VCCO3
3	83P	M26	N26	-	M27	—	H19
3	84N	M28	N25	-	M29	—	G20
3	84P	M30	N24	-	M31	—	G19
-	-	GND	-	-	-	GND	GND
3	85N	N0	N23	-	N1	—	C22
-	-	VCC	-	-	-	VCC	VCC
3	85P	N2	N22	-	N3	—	C21
3	86N	N4	N21	-	-	—	D20
3	86P	N6	N20	-	-	—	C19
3	87N	N8	N19	-	N9	C16	F19
3	87P	N10	N18	-	N11	B16	E19
-	-	GND (Bank 3)	-	-	-	GND (Bank 3)	GND (Bank 3)
3	88N	N12	N17	-	N13	C15	G18
-	-	VCCO3	-	-	-	VCCO3	VCCO3
3	88P	N14	N16	-	N15	B15	F18
3	89N	N16	N15	-	N17	E14	B20
3	89P	N18	N14	-	N19	D14	B19
3	90N	N20	N13	-	N21	E13	A20
3	90P	N22	N12	-	N23	A15	A19
3	91N	N24	P19	N19	N25	D12	D18
3	91P	N26	P18	N18	N27	B14	C18
3	92N	N28	P17	N17	N29	C13	G17
3	92P	N30	P16	N16	N31	A14	F16

ispXPLD 51024MX Logic Signal Connections (Continued)

sysIO Bank	LVDS Pair	Primary Macrocell/Function	Alternate Outputs		Alternate Input	484 fpBGA Ball Number	672 fpBGA Ball Number
			Macrocell 1	Macrocell 2			
0	175N	AC22	AC27	AE27	AC23	K6	J5
-	-	VCCO0	-	-	-	VCCO0	VCCO0
0	175P	AC20	AC26	AE26	AC21	K3	J4
-	-	GND (Bank 0)	-	-	-	GND (Bank 0)	GND (Bank 0)
0	176N	AC18	AC25	AE25	AC19	K5	K7
0	176P	AC16	AC24	AE24	AC17	K2	L7
0	177N	AC14	AC23	AE23	AC15	L5	J3
0	177P	AC12	AC22	AE22	AC13	K1	J2
0	178N	AC10	AC21	AE21	AC11	L6	K6
0	178P	AC8	AC20	AE20	AC9	L1	L6
0	179N	AC6	AC19	AE19	AC7	M5	K5
0	179P	AC4	AC18	AE18	AC5	L2	K4
0	180N	AC2	AC17	AE17	AC3	N5	K3
-	-	VCCO0	-	-	-	VCCO0	VCCO0
0	180P	AC0	AC16	AE16	AC1	L3	K2
-	-	GND (Bank 0)	-	-	-	GND (Bank 0)	GND (Bank 0)
0	181N	AE30	AC15	AE15	AE31	M6	K1
0	181P	AE28	AC14	AE14	AE29	M2	L2
0	182N	AE26	AC13	AE13	AE27	P5	L5
-	-	VCC	-	-	-	VCC	VCC
0	182P	AE24	AC12	AE12	AE25	P6	L4
0	183N	AE22	AC11	AE11	AE23	M3	L3
0	183P	AE20	AC10	AE10	AE21	N6	M3
0	184N	AE18	AC9	AE9	AE19	N2	M7
0	184P	AE16	AC8	AE8	AE17	P1	N7
-	-	GND	-	-	-	GND	GND
0	185N	AE14	AC7	AE7	AE15	N3	M5
-	-	VCCO0	-	-	-	VCCO0	VCCO0
0	185P	AE12	AC6	AE6	AE13	M8	M4
-	-	GND (Bank 0)	-	-	-	GND (Bank 0)	GND (Bank 0)
0	186N	AE10	AC5	AE5	AE11	N8	M6
0	186P	AE8	AC4	AE4	AE9	P2	N6
0	187N	AE6	AC3	AE3	AE7	P8	M2
0	187P	AE4	AC2	AE2	AE5	N4	M1
0	188N	AE2	AC1	AE1	AE3	H1	N1
0	188P	AE0	AC0	AE0	AE1	J1	N2
-	GCLK0P	GCLK0	-	-	-	N7	N5
-	-	VCCJ	-	-	-	See Power Supply and NC Connections Table	
-	GCLK0N	GCLK1	-	-	-	P7	N3
-	-	GND	-	-	-	GND	GND
-	-	TDI	-	-	-	R1	P4
-	-	TMS	-	-	-	R2	P5

ispXPLD 51024MX Logic Signal Connections (Continued)

sysIO Bank	LVDS Pair	Primary Macrocell/Function	Alternate Outputs		Alternate Input	484 fpBGA Ball Number	672 fpBGA Ball Number
			Macrocell 1	Macrocell 2			
-	-	TCK	-	-	-	T1	P3
-	-	TDO	-	-	-	V1	P2
1	0P	A30	A0	C0	A31	—	P1
1	0N	A28	A1	C1	A29	—	R1
1	1P	A26	A2	C2	A27	—	P6
1	1N	A24	A3	C3	A25	—	R6
1	2P	A22	A4	C4	A23	—	P7
1	2N	A20	A5	C5	A21	—	R7
-	-	GND (Bank 1)	-	-	-	GND (Bank 1)	GND (Bank 1)
1	3P	A18	A6	C6	A19	—	R4
-	-	VCCO1	-	-	-	VCCO1	VCCO1
1	3N	A16	A7	C7	A17	—	R5
-	-	GND	-	-	-	GND	GND
1	4P	A14	A8	C8	A15	—	R3
-	-	VCC	-	-	-	VCC	VCC
1	4N	A12	A9	C9	A13	—	R2
1	5P	A10	A10	C10	A11	—	T2
1	5N	A8	A11	C11	A9	—	T3
1	6P	A6	A12	C12	A7	—	T4
1	6N	A4	A13	C13	A5	—	T5
1	7P	A2	A14	C14	A3	—	U2
1	7N	A0	A15	C15	A1	—	U3
-	-	GND (Bank 1)	-	-	-	GND (Bank 1)	GND (Bank 1)
1	8P	C30	A16	C16	C31	—	U4
-	-	VCCO1	-	-	-	VCCO1	VCCO1
1	8N	C28	A17	C17	C29	—	U5
1	9P	C26	A18	C18	C27	—	T6
1	9N	C24	A19	C19	C25	—	U6
1	10P	C22	A20	C20	C23	—	T7
1	10N	C20	A21	C21	C21	—	U7
1	11P	C18	A22	C22	C19	—	U1
1	11N	C16	A23	C23	C17	—	V1
1	12P	C14	A24	C24	C15	—	V2
1	12N	C12	A25	C25	C13	—	V3
-	-	GND (Bank 1)	-	-	-	GND (Bank 1)	GND (Bank 1)
1	13P	C10	A26	C26	C11	—	V5
-	-	VCCO1	-	-	-	VCCO1	VCCO1
1	13N	C8	A27	C27	C9	—	V4
-	-	GND	-	-	-	GND	GND
1	14P	C6	A28	C28	C7	—	W2
-	-	VCC	-	-	-	VCC	VCC
1	14N	C4	A29	C29	C5	—	W3
1	15P	C2	A30	C30	C3	—	W4

ispXPLD 51024MX Logic Signal Connections (Continued)

sysIO Bank	LVDS Pair	Primary Macrocell/Function	Alternate Outputs		Alternate Input	484 fpBGA Ball Number	672 fpBGA Ball Number
			Macrocell 1	Macrocell 2			
-	-	GND (Bank 3)	-	-	-	GND (Bank 3)	GND (Bank 3)
3	110N	U4	X25	V25	U5	H21	J21
-	-	VCCO3	-	-	-	VCCO3	VCCO3
3	110P	U6	X24	V24	U7	G21	H21
-	-	GND	-	-	-	GND	GND
3	111N	U8	X23	V23	U9	D22	G25
3	111P	U10	X22	V22	U11	D21	G24
3	112N	U12	X21	V21	U13	J20	G23
3	112P	U14/CLK_OUT1	X20	V20	U15	J19	G22
3	113N	U16	V31	-	U17	E20	J20
-	-	VCC	-	-	-	VCC	VCC
3	113P	U18	V30	U30	U19	F20	H20
3	114N	U20	V29	U28	U21	H17	G26
3	114P	U22	V28	U26	U23	H18	F25
-	-	GND (Bank 3)	-	-	-	GND (Bank 3)	GND (Bank 3)
3	115N	U24	V27	-	U25	J18	F24
-	-	VCCO3	-	-	-	VCCO3	VCCO3
3	115P	U26	V26	-	U27	H19	F23
3	116N	U28	V25	-	U29	G20	G21
3	116P	U30	V24	-	U31	G19	F22
-	-	GND	-	-	-	GND	GND
3	117N	V0	V23	-	V1	C22	F26
-	-	VCC	-	-	-	VCC	VCC
3	117P	V2	V22	-	V3	C21	E26
3	118N	V4	V21	-	V5	D20	E25
3	118P	V6	V20	-	V7	C19	E24
3	119N	V8	V19	-	V9	F19	E23
3	119P	V10	V18	-	V11	E19	E22
-	-	GND (Bank 3)	-	-	-	GND (Bank 3)	GND (Bank 3)
3	120N	V12	V17	-	V13	G18	D26
-	-	VCCO3	-	-	-	VCCO3	VCCO3
3	120P	V14	V16	-	V15	F18	D25
3	121N	V16	V15	-	V17	B20	D24
3	121P	V18	V14	-	V19	B19	D23
3	122N	V20	V13	-	V21	A20	C26
3	122P	V22	V12	-	V23	A19	C25
3	123N	V24	X19	V19	V25	D18	G19
3	123P	V26	X18	V18	V27	C18	F19
3	124N	V28	X17	V17	V29	G17	G18
3	124P	V30	X16	V16	V31	F16	F18
3	125N	W0	X31	V31	W1	E17	F20
3	125P	W2	X30	V30	W3	D17	E20
-	-	GND (Bank 3)	-	-	-	GND (Bank 3)	GND (Bank 3)

Global Clock LVDS pair options: GCLK0 and GCLK1, as well as GCLK2 and GCLK3, can be paired together to receive differential clocks; where GCLK0 and GCLK3 are the positive LVDS inputs.